


PATENT NUMBER

ISSUE CLASSIFICATION	
Class	Subclass

**U.S. UTILITY Patent Application**

 <div style="text-align: center;">O.I.P.E.</div> <div> SCANNED <u>TR3</u> O.A. <u>Am</u> </div>	<div style="text-align: center;">PATENT DATE</div>
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APPLICATION NO. 09/964709	CONT/PRIOR	CLASS 257	SUBCLASS 706	ART UNIT 2814	EXAMINER CHAMBLISS <i>[Signature]</i>
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## APPLICANTS

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# אנדר

Method of improving thermal performance in flip chip/integral heat spreader packages using low modulus thermal interface material

PTO-2040  
12/99

**ISSUING CLASSIFICATION**

[illegible]

<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>	<b>DRAWINGS</b>		<b>CLAIMS ALLOWED</b>	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner)		<b>NOTICE OF ALLOWANCE MAILED</b> _____	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Primary Examiner)		<b>ISSUE FEE</b> Amount Due      Date Paid	
	_____ (Legal Instruments Examiner)		<b>ISSUE BATCH NUMBER</b> _____	
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